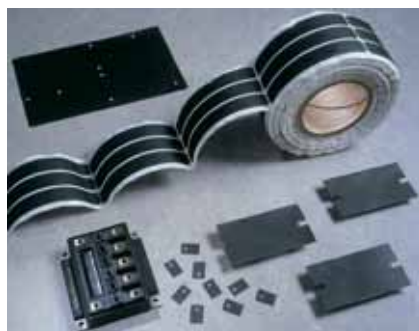


Glass-Reinforced Grease Replacement Thermal Interface

Features and Benefits

- Thermal impedance:
0.35°C-in²/W (@50 psi)
- Eliminates processing constraints typically associated with grease
- Conforms to surface textures
- Easy handling
- May be installed prior to soldering and cleaning without worry



Bergquist Q-Pad 3 eliminates problems associated with thermal grease such as contamination of electronic assemblies and reflow solder baths. Q-Pad 3 may be installed prior to soldering and cleaning without worry. When clamped between two surfaces, the elastomer conforms to surface textures thereby creating an air-free interface between heat-generating components and heat sinks.

Fiberglass reinforcement enables Q-Pad 3 to withstand processing stresses without losing physical integrity. It also provides ease of handling during application.

TYPICAL PROPERTIES OF Q-PAD 3						
PROPERTY		IMPERIAL VALUE		METRIC VALUE		TEST METHOD
Color		Black		Black		Visual
Reinforcement Carrier		Fiberglass		Fiberglass		—
Thickness (inch) / (mm)		0.005		0.127		ASTM D374
Hardness (Shore A)		86		86		ASTM D2240
Continuous Use Temp (°F) / (°C)		-76 to 356		-60 to 180		—
ELECTRICAL						
Dielectric Breakdown Voltage (Vac)		Non-Insulating		Non-Insulating		ASTM D149
Dielectric Constant (1000 Hz)		NA		NA		ASTM D150
Volume Resistivity (Ohm-meter)		10 ²		10 ²		ASTM D257
Flame Rating		V-O		V-O		U.L.94
THERMAL						
Thermal Conductivity (W/m-K)		2.0		2.0		ASTM D5470
THERMAL PERFORMANCE vs PRESSURE						
Pressure (psi)		10	25	50	100	200
TO-220 Thermal Performance (°C/W)		2.26	1.99	1.76	1.53	1.30
Thermal Impedance (°C-in ² /W) (1)		0.65	0.48	0.35	0.24	0.16
1) The ASTM D5470 test fixture was used.The recorded value includes interfacial thermal resistance. These values are provided for reference only Actual application performance is directly related to the surface roughness, flatness and pressure applied.						

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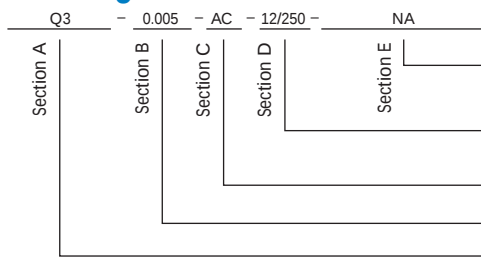
Typical Applications Include:

- Between a transistor and a heat sink
- Between two large surfaces such as an L-bracket and the chassis of an assembly
- Between a heat sink and a chassis
- Under electrically isolated power modules or devices such as resistors, transformers and solid state relays

Configurations Available:

- Sheet form, die-cut parts and roll form
- With or without pressure sensitive adhesive

Building a Part Number



Standard Options

◀ example

NA = Selected standard option. If not selecting a standard option, insert company name, drawing number, and revision level.

1212 = Standard configuration dash number, 1212 = 12" x 12" sheets, 12/250 = 12" x 250' rolls, or 00 = custom configuration

AC = Adhesive, one side
00 = No adhesive

Standard thicknesses available: 0.005"

Q3 = Q-Pad 3 Material

Note: To build a part number, visit our website at www.bergquistcompany.com.

Sil-Pad®: U.S. Patents 4,574,879; 4,602,125; 4,602,678; 4,685,987; 4,842,911 and others



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<http://moschip.ru/get-element>

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В нашем ассортименте представлены ведущие мировые производители активных и пассивных электронных компонентов.

Нашей специализацией является поставка электронной компонентной базы двойного назначения, продукции таких производителей как XILINX, Intel (ex.ALTERA), Vicor, Microchip, Texas Instruments, Analog Devices, Mini-Circuits, Amphenol, Glenair.

Сотрудничество с глобальными дистрибьюторами электронных компонентов, предоставляет возможность заказывать и получать с международных складов практически любой перечень компонентов в оптимальные для Вас сроки.

На всех этапах разработки и производства наши партнеры могут получить квалифицированную поддержку опытных инженеров.

Система менеджмента качества компании отвечает требованиям в соответствии с ГОСТ Р ИСО 9001, ГОСТ РВ 0015-002 и ЭС РД 009

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